

MATERIAL DECLARATION SHEET



Material Number	PTVS10-470C-TH			
Product Line	Semiconductor Products			
Compliance Date	September 1 st 2014			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.973600	Bisphenol Copolymer	1675-54-3	60.00	3.99	6.65
				Alumina Trihydrate	25085-99-8	15.00	1.00	
				Fused Silica	14464-46-1	20.00	1.33	
				Hydrated Iron Oxide	40039-93-8	1.50	0.10	
				Titanium Dioxide	51274-00-1	1.50	0.10	
				Melamine Cyanurate	13463-67-7	1.50	0.10	
				Amine Adduct	Trade Secret	0.50	0.03	
2	Electrodes	Copper	10.579893	Copper	7440-50-8	99.10	71.65	72.30
				Silver	7440-22-4	0.40	0.29	
				Other	-	0.50	0.36	
3	Terminations	Copper	0.441398	Copper	7440-50-8	99.50	3.00	3.02
				Other	-	0.50	0.02	
4	Termination Finish	Silver	0.001730	Silver	7440-22-4	100.00	0.01	0.01
5	Chip	Silicon Die	1.250790	Silicon	7440-21-3	85.73	7.33	8.55
				Aluminium	7429-90-5	4.99	0.43	
				Nickel	7440-02-0	8.85	0.76	
				Gold	7440-57-5	0.43	0.04	
6	Die Attach	Solder	0.764770	Lead	7439-92-1	92.50	4.83	5.23
				Tin	7440-31-5	5.00	0.26	
				Silver	7440-22-4	2.50	0.13	
7	Die Coating	Silicone	0.620180	Polysiloxane	63148-62-9	22.11	0.94	4.24
				Chromium Sesquioxide	1308-38-9	5.67	0.24	
				Fumed Silica	112945-52-5	11.11	0.47	
				Filler	trade secret	61.11	2.59	
		Total Weight	14.632361					